

**Product Data Sheet / Produkt Datenblatt**

**Part Number**

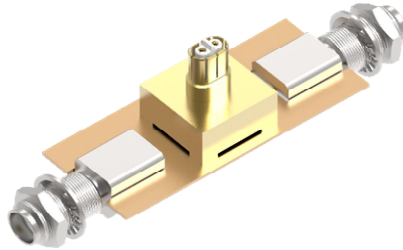
**AGK-4741**

**Teilenummer**

**Description**

**Messadapter Kit für HTP Serie  
 Measuring adapter kit for HTP series**

**Beschreibung**



**Design according to**

**Ausführung nach**

**Electrical characteristics / Elektrische Eigenschaften**

		colored value means: under validation			
		Value/Wert	Unit/ Einheit		
Impedance (MIL-C-39012B)		100 ±5	[Ω]		Impedanz (MIL-C-39012B)
Operating frequency		10	[GHz]		Betriebsfrequenz
Data rate		20	[Gbit/sec]		Datenrate
Return loss	DC-4 GHz	- 21			Rückflusdämpfung
	4-6 GHz	- 20	[dB]		
	6-10 GHz	- 12	[dB]		
Insertion Loss	DC-10 GHz	≤ 0,5	[dB]		Einfügedämpfung
Insulation resistance		1	[GΩ]		Isolationswiderstand
Contact resistance					Kontakt-Widerstand
Centre contact		15,0	[mΩ]		Innenkontakt
Outer contact		7,5	[mΩ]		Außenkontakt
Operating voltage		max.60	[V] DC		Betriebsspannung
Proof voltage		500	[V] eff		Prüfspannung

**Mechanical characteristics / Mechanische Eigenschaften**

		Value/ Wert	Unit/ Einheit		
Mating cycles		- 500	[-]		Steckzyklen
Mating force		max. 10	[N]		Steckkraft
Unmating force		max. 10	[N]		Trennkraft

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### Material & plating / Material & Oberfläche

	Material/Material	Plating/Oberflächen	
Federkorb	Bronze	Au	Spring basket
Insulator	SPS		Isolator
Centre contact	CuBe	Au	Innenkontakt

### Environmental influences

### Umwelteinflüsse

Temperature range	-40°C up to +125°C	Temperaturbereich
Vibration	MIL-STD-202 Meth. 204, cond.B	Vibration
Corrosion resistance	MIL-STD-202 Meth. 101, cond.D	Korrosionsbeständigkeit
Climatic categorie	IC 60068 65/85/21	Klimakategorie
Shock	MIL-STD-202 Meth. 213, cond. G	Schock
Max. soldering temp. (PCB connectors)	IEC 61760-1, +260°C for 10 sec.	Max. Löttemp. (Leiterplattenanschlüsse)
RoHS		RoHS
Solder profile		Lötprofil

### Notes

### Aufzeichnungen

\* Higher cross talk performance can be achieved with certain precautions

\*\* Connector performance strongly depends on PCB type and layout